Switch-mode Power Rectifier 60 V, 20 A

MBR20L60CTG MBRF20L60CTG

Features and Benefits

- Low Power Loss/High Efficiency
- High Surge Capacity
- 20 A Total (10 A Per Diode Leg)
- Guard-Ring for Stress Protection
- These Devices are Pb-Free and are RoHS Compliant*

Applications

- Power Supply Output Rectification
- Power Management
- Instrumentation

Mechanical Characteristics:

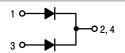
- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 Units Per Plastic Tube



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SCHOTTKY BARRIER RECTIFIER 20 AMPERES 60 VOLTS



TO-220

CASE 221A

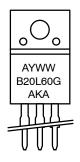
STYLE 6



MARKING DIAGRAM

AYWW B20L60G AKA





A = Assembly Location

Y = Year
WW = Work Week
B20L60 = Device Code
G = Pb-Free Package
AKA = Polarity Designator

ORDERING INFORMATION

Device	Package	Shipping
MBR20L60CTG	TO-220 (Pb-Free)	50 Units / Rail
MBRF20L60CTG	TO-220FP (Pb-Free)	50 Units / Rail

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS (Per Diode Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60	V
	I _{F(AV)}	10 20	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	240	А
Operating Junction Temperature (Note 1)	TJ	-55 to +150	°C
Storage Temperature	T _{stg}	- 65 to +175	°C
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V
Maximum Repetitive Peak Avalanche Voltage $(t_p < 1~\mu s, T_J < 150^{\circ}C, I_{AR} < 51~A)$	V_{ARM}	85	V
Maximum Single–Pulse Peak Avalanche Voltage $(t_p < 1~\mu s, T_J < 150^{\circ}C, I_{AR} < 51~A)$	V _{ASM}	85	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

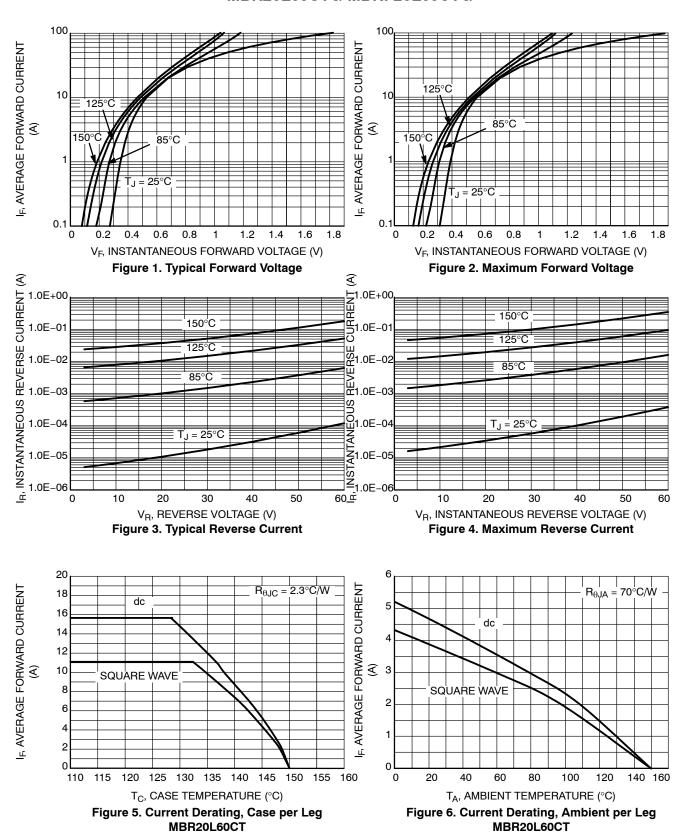
Characte	Symbol	Value	Unit	
Maximum Thermal Resistance				°C/W
MBR20L60CTG	Junction-to-Case	$R_{ heta JC}$	2.3	
	Junction-to-Ambient	$R_{ hetaJA}$	70	
MBRF20L60CTG	Junction-to-Case	$R_{ heta JC}$	5.2	
	Junction-to-Ambient	$R_{ hetaJA}$	75	

ELECTRICAL CHARACTERISTICS (Per Diode Leg)

Characteristic	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) $ \begin{aligned} &(I_F=10\text{ A}, T_C=25^\circ\text{C})\\ &(I_F=10\text{ A}, T_C=125^\circ\text{C})\\ &(I_F=20\text{ A}, T_C=25^\circ\text{C})\\ &(I_F=20\text{ A}, T_C=125^\circ\text{C}) \end{aligned} $	VF	0.53 0.49 0.68 0.64	0.57 0.54 0.73 0.69	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_C = 25^{\circ}C$) (Rated DC Voltage, $T_C = 125^{\circ}C$)	i _R	118 52	380 96	μA mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

^{1.} The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.



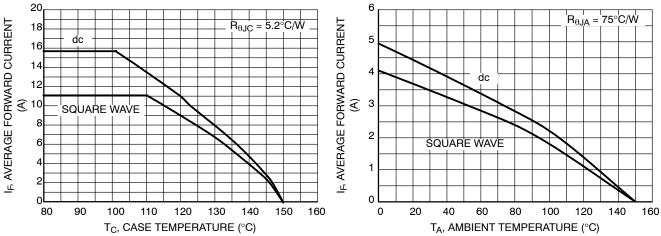


Figure 7. Current Derating, Case per Leg MBRF20L60CT

Figure 8. Current Derating, Ambient per Leg MBRF20L60CT

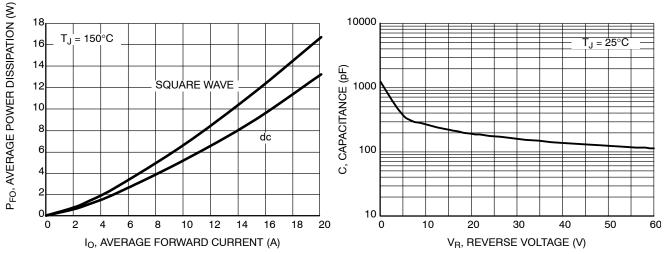


Figure 9. Forward Power Dissipation

Figure 10. Capacitance

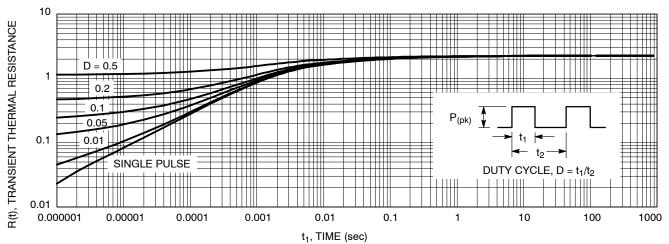


Figure 11. Thermal Response Junction-to-Case, per Leg for MBR20L60CT

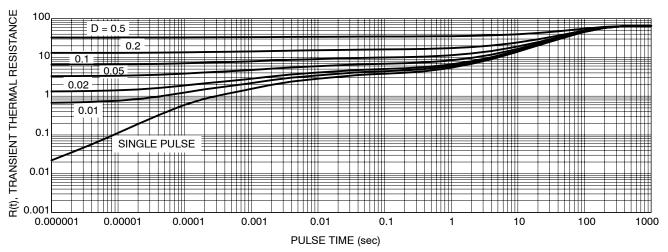


Figure 12. Thermal Response Junction-to-Ambient, per Leg for MBR20L60CT

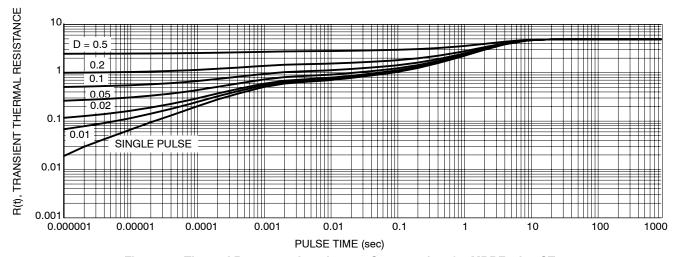


Figure 13. Thermal Response Junction-to-Case, per Leg for MBRF20L60CT

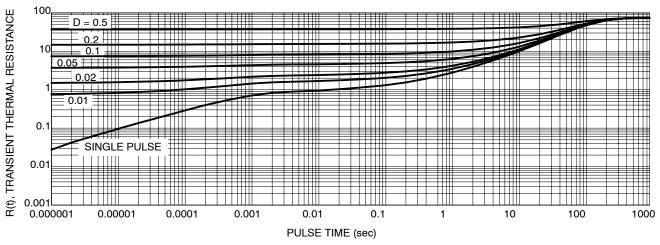
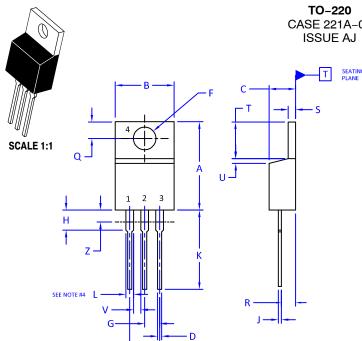


Figure 14. Thermal Response Junction-to-Ambient, per Leg for MBRF20L60CT

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MECHANICAL CASE OUTLINE



CASE 221A-09

DATE 05 NOV 2019

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: INCHES
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCHES		MILLIMETERS	
DIM	MIN.	MAX.	MIN.	MAX.
Α	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.60	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
К	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.41
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:	
PIN 1.	BASE	PIN 1.	BASE	PIN 1.	CATHODE	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	EMITTER	2.	ANODE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	COLLECTOR	3.	GATE	3.	GATE
4.	COLLECTOR	4.	EMITTER	4.	ANODE	4.	MAIN TERMINAL 2
STYLE 5:		STYLE 6:		STYLE 7:		STYLE 8:	
PIN 1.	GATE	PIN 1.	ANODE	PIN 1.	CATHODE	PIN 1.	CATHODE
2.	DRAIN	2.	CATHODE	2.	ANODE	2.	ANODE
3.	SOURCE	3.	ANODE	3.	CATHODE	3.	EXTERNAL TRIP/DELAY
4.	DRAIN	4.	CATHODE	4.	ANODE	4.	ANODE
STYLE 9:		STYLE 10:		STYLE 11	:	STYLE 12	:
PIN 1.	GATE	PIN 1.	GATE	PIN 1.	DRAIN	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	SOURCE	2.	SOURCE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	DRAIN	3.	GATE	3.	GATE
4.	COLLECTOR	4.	SOURCE	4.	SOURCE	4.	NOT CONNECTED

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MECHANICAL CASE OUTLINE





SCALE 1:1

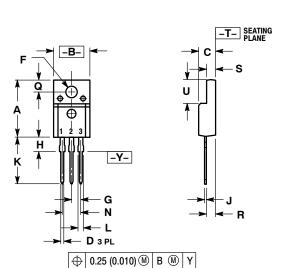
TO-220 FULLPAK CASE 221D-03 ISSUE K

DATE 27 FEB 2009



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH
- 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.617	0.635	15.67	16.12
В	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
Н	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200	BSC	5.08	BSC
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88



MARKING DIAGRAMS

STYLE 1: PIN 1. GATE 2. DRAIN 3. SOURCE

STYLE 4: PIN 1. CATHODE

3. CATHODE

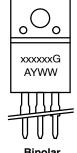
ANODE

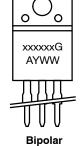
STYLE 2: PIN 1. BASE 2. COLLECTOR 3. EMITTER 2.

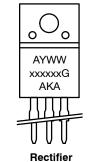
STYLE 6: PIN 1. MT 1 2. MT 2 3. GATE STYLE 5: PIN 1. CATHODE 2. ANODE 3. GATE

STYLE 3: PIN 1. ANODE

CATHODE
 ANODE







= Assembly Location xxxxxx = Specific Device Code G = Pb-Free Package Υ = Year

= Assembly Location WW = Work Week = Year XXXXXX = Device Code = Work Week = Pb-Free Package WW G AKA = Polarity Designator

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